Abstracts

Microwave Module Packaging

G. Jerinic and M. Borkowski. "Microwave Module Packaging." 1992 MTT-S International Microwave Symposium Digest 92.3 (1992 Vol. III [MWSYM]): 1503-1506.

The demonstration of a <$50 package for GaAs MMIC microwave module applications has not been achieved yet. This paper outlines the requirements for microwave packaging and describes three low-cost metal-package solutions (1) brazed construction, (2) metal injection molded construction, and (3) pressure infiltration casting.

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